

**Date:** February 2021  
**Rev:** X  
**No. of Components:** Two  
**Mix Ratio by Weight:** 100 : 4  
**Specific Gravity:** Part A: 2.03      Part B: 1.02  
**Pot Life:** 2.5 Hours  
**Shelf Life- Bulk:** One year at room temperature

**Recommended Cure: 150°C / 1 Hour**

Minimum Alternative Cure(s):  
*May not achieve performance properties listed below*  
 150°C / 10 Minutes  
 100°C / 20 Minutes  
 80°C / 2 Hours

**NOTES:**

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.

**Product Description:** EPO-TEK® H73 is a two component, thermally conductive, electrically insulating epoxy. It is a higher viscosity alternative to EPO-TEK® H74.

**Typical Properties:** Cure condition: 150°C / 1 Hour      Different batches, conditions & applications yield differing results.  
 Data below is not guaranteed. To be used as a guide only, not as a specification. \* denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	Part A: Light grey	Part B: Amber	
* Consistency:	Thick paste		
* Viscosity (23°C) @ 2.5 rpm:	80,000-100,000	cPs	
Thixotropic Index:	Not Measurable		
* Glass Transition Temp:	≥ 100	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expansion (CTE):			
	Below Tg:	35	x 10 <sup>-6</sup> in/in°C
	Above Tg:	98	x 10 <sup>-6</sup> in/in°C
Shore D Hardness:	91		
Lap Shear @ 23°C:	1,952	psi	
Die Shear @ 23°C:	≥ 10	Kg	3,556 psi
Degradation Temp:	428	°C	
Weight Loss:			
	@ 200°C:	0.13	%
	@ 250°C:	0.21	%
	@ 300°C:	0.47	%
Suggested Operating Temperature:	< 350	°C (Intermittent)	
Storage Modulus:	875,539	psi	
* Particle Size:	≤ 50	microns	

ELECTRICAL AND THERMAL PROPERTIES:			
Thermal Conductivity:	0.8	W/mK	
Volume Resistivity @ 23°C:	≥ 3 x 10 <sup>13</sup>	Ohm-cm	
Dielectric Constant (1KHz):	5.17		
Dissipation Factor (1KHz):	0.008		

**Epoxyes and Adhesives for Demanding Applications™**

**This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.**

**EPOXY TECHNOLOGY, INC.**

**14 FORTUNE DRIVE, BILLERICA, MA 01821 (978) 667-3805, FAX (978) 663-9782**

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**EPO-TEK® H73 Advantages & Suggested Application Notes:**

- Thixotropic paste allows for good handling characteristics - it can be dispensed, screen printed or manually applied by toothpick or spatula.
- Outstanding high temperature properties and excellent solvent, chemical and moisture resistance.
- Reasonable working life with fast curing at relatively low temperatures.
- Capable of providing near-hermetic seal.
- NASA approved, low outgassing epoxy – <http://outgassing.nasa.gov/>
- Built in color indicator when product is cured. Color change may vary from tan to brown depending on cure conditions. Epoxy may turn dark red when subjected to wire bonding temperatures.

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